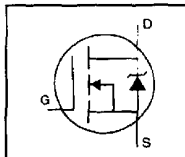


HEXFET® Power MOSFET

- Ultra Low Gate Charge
- Reduced Gate Drive Requirement
- Enhanced 30V V_{GS} Rating
- Reduced C_{iss} , C_{oss} , C_{rss}
- Extremely High Frequency Operation
- Repetitive Avalanche Rated



$$V_{DS} = 400V$$

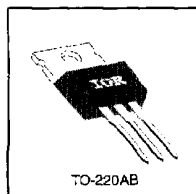
$$R_{DS(on)} = 0.55\Omega$$

$$I_D = 10A$$

Description

This new series of Low Charge HEXFETs achieve significantly lower gate charge over conventional MOSFETs. Utilizing the new LCDMOS technology, the device improvements are achieved without added product cost, allowing for reduced gate drive requirements and total system savings. In addition, reduced switching losses and improved efficiency are achievable in a variety of high frequency applications. Frequencies of a few MHz at high current are possible using the new Low Charge MOSFETs.

These device improvements combined with the proven ruggedness and reliability that are characteristic of HEXFETs offer the designer a new standard in power transistors for switching applications.



Absolute Maximum Ratings

Parameter	Max.	Units
I_D @ $T_C = 25^\circ C$ Continuous Drain Current, $V_{GS} \geq 10V$	10	A
I_D @ $T_C = 100^\circ C$ Continuous Drain Current, $V_{GS} \geq 10V$	6.3	A
I_{DM} Pulsed Drain Current ①	32	A
P_D @ $T_C = 25^\circ C$ Power Dissipation	125	W
Linear Derating Factor	1.0	W/°C
V_{GS} Gate-to-Source Voltage	± 33	V
E_{AS} Single Pulse Avalanche Energy ②	520	mJ
I_{AR} Avalanche Current ③	10	A
E_{AR} Repetitive Avalanche Energy ③	13	mJ
dv/dt Peak Diode Recovery dv/dt ③	4.0	V/ns
T_J Operating Junction and Storage Temperature Range	-55 to +150	°C
T_{STG} Soldering Temperature, for 10 seconds	300 (1.6mm from case)	°C
Mounting Torque, 6-32 or M3 screw	10 lb-in (1.1 N-m)	

Thermal Resistance

Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$ Junction-to-Case	—	—	1.0	°C/W
$R_{\theta CS}$ Case-to-Sink, Flat, Greased Surface	—	0.50	—	°C/W
$R_{\theta JA}$ Junction-to-Ambient	—	—	62	°C/W

IRF740LC



Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Parameter	Min.	Typ.	Max.	Units	Test Conditions
$V_{DS(BR)SS}$	400	—	—	V	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$
$\Delta V_{DS(BR)SS}/\Delta T_J$	—	0.75	—	$\text{V}/^\circ\text{C}$	Reference to 25°C , $I_D=1\text{mA}$
$R_{DS(on)}$	—	—	0.55	Ω	$V_{GS}=10\text{V}$, $I_D=6.0\text{A}$ ①
$V_{GS(th)}$	2.0	—	4.0	V	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$
g_{fs}	3.0	—	—	S	$V_{DS}=50\text{V}$, $I_D=6.0\text{A}$ ①
I_{DSS}	—	—	25	μA	$V_{DS}=400\text{V}$, $V_{GS}=0\text{V}$
I_{DSS}	—	—	250	μA	$V_{DS}=320\text{V}$, $V_{GS}=0\text{V}$, $T_J=125^\circ\text{C}$
I_{DSS}	—	—	100	nA	$V_{GS}=20\text{V}$
I_{DSS}	—	—	100	nA	$V_{GS}=20\text{V}$
Q_g	—	—	39	nC	$I_D=10\text{A}$
Q_{GS}	—	—	10	nC	$V_{DS}=320\text{V}$
Q_{GD}	—	—	19	nC	$V_{GS}=10\text{V}$ See Figure 6 and 13 ①
$t_{d(on)}$	—	11	—	ns	$V_{DS}=200\text{V}$
t_r	—	31	—	ns	$I_D=10\text{A}$
$t_{d(off)}$	—	25	—	ns	$R_G=9.1\Omega$
t_f	—	20	—	ns	$R_D=20\Omega$ See Figure 10 ①
L_D	—	4.5	—	nH	Between lead, 6 mm (0.25 in.) from package and center of die contact
L_S	—	7.5	—	nH	
C_{iss}	—	1100	—	pF	$V_{GS}=0\text{V}$
C_{oss}	—	190	—	pF	$V_{DS}=25\text{V}$
C_{rss}	—	18	—	pF	$f=1\text{MHz}$ See Figure 5

Source-Drain Ratings and Characteristics

Parameter	Min.	Typ.	Max.	Units	Test Conditions
I_S	—	—	10	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	—	—	32	A	
V_{SD}	—	—	2.0	V	$T_J=25^\circ\text{C}$, $I_S=10\text{A}$, $V_{GS}=0\text{V}$ ①
t_{rr}	—	380	570	ns	$T_J=25^\circ\text{C}$, $I_S=10\text{A}$
Q_{rr}	—	2.8	4.2	μC	$dI/dt=100\text{A}/\mu\text{s}$ ①
t_{on}	—	—	—	ns	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)

Notes:

① Repetitive rating; pulse width limited by max. junction temperature (See Figure 11)

② $I_{DS} \leq 10\text{A}$, $dI/dt \leq 120\text{A}/\mu\text{s}$, $V_{DS} \leq V_{DS(BR)SS}$, $T_J \leq 150^\circ\text{C}$

③ $V_{DD}=50\text{V}$, starting $T_J=25^\circ\text{C}$, $L=9.1\text{mH}$, $R_G=25\Omega$, $I_{AS}=10\text{A}$ (See Figure 12)

④ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

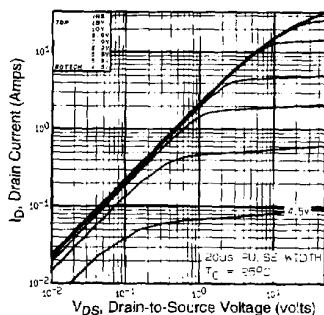


Fig 1. Typical Output Characteristics,
 $T_C = 25^\circ\text{C}$

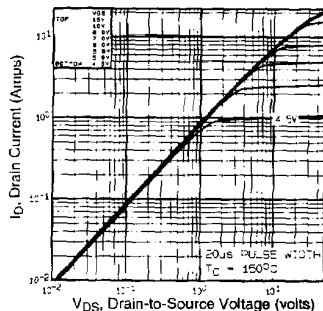


Fig 2. Typical Output Characteristics,
 $T_C = 150^\circ\text{C}$

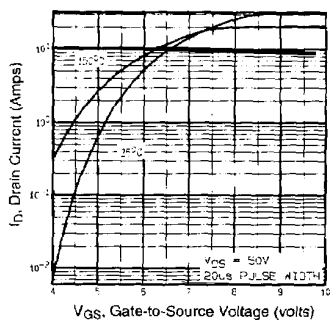


Fig 3. Typical Transfer Characteristics

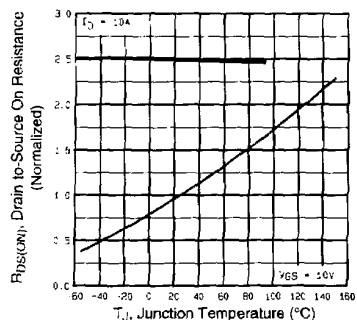


Fig 4. Normalized On-Resistance
Vs. Temperature

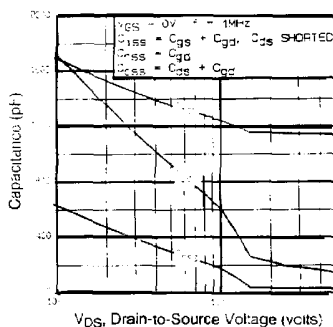


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

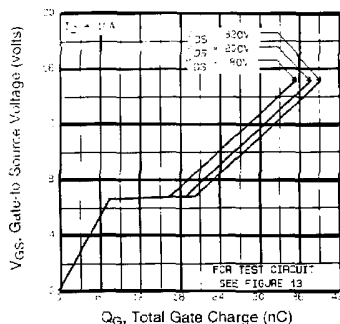


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

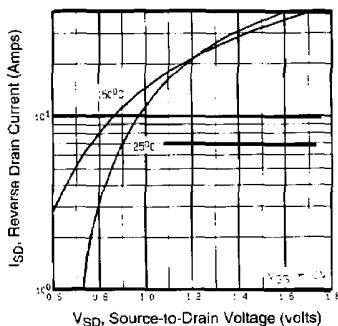


Fig 7. Typical Source-Drain Diode Forward Voltage

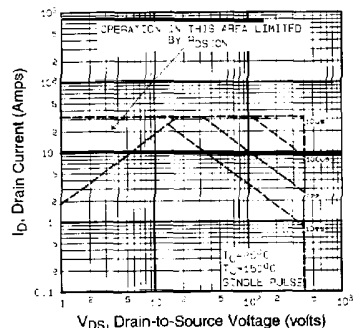


Fig 8. Maximum Safe Operating Area

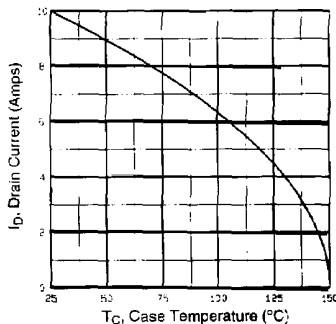


Fig 9. Maximum Drain Current Vs. Case Temperature

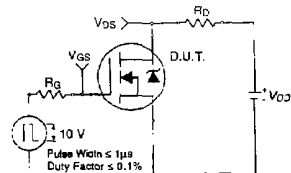


Fig 10a. Switching Time Test Circuit

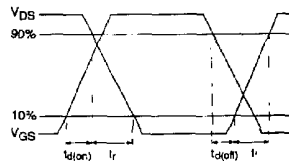


Fig 10b. Switching Time Waveforms

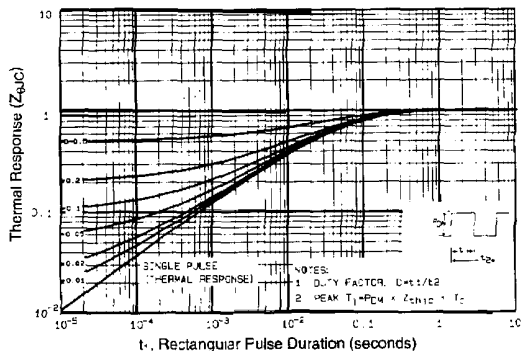


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

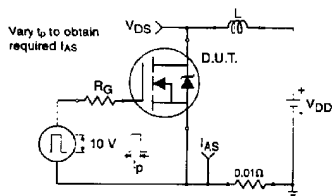


Fig 12a. Unclamped Inductive Test Circuit

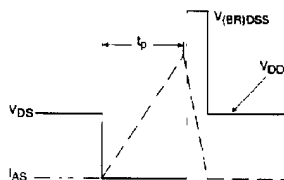


Fig 12b. Unclamped Inductive Waveforms

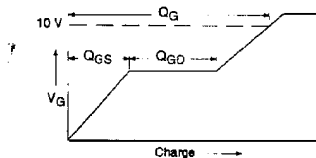


Fig 13a. Basic Gate Charge Waveform

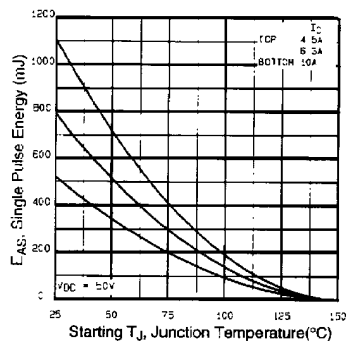


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

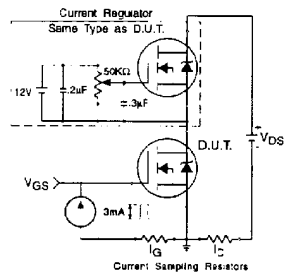


Fig 13b. Gate Charge Test Circuit

Appendix A: Figure 14, Peak Diode Recovery dv/dt Test Circuit

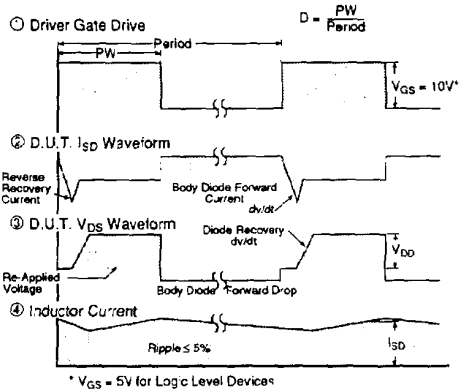
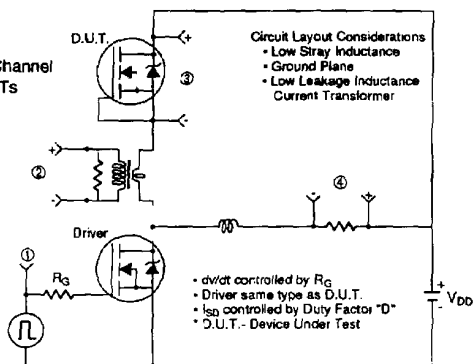
Appendix B: Package Outline Mechanical Drawing

Appendix C: Part Marking Information

Appendix A

Peak Diode Recovery dv/dt Test Circuit

Fig 14. For N-Channel HEXFETs



IRF740LC

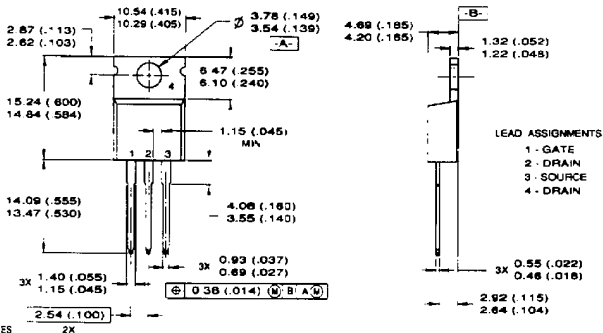


Package Outline

Appendix B

TO-220AB Outline

Dimensions are shown in millimeters (inches)



NOTES

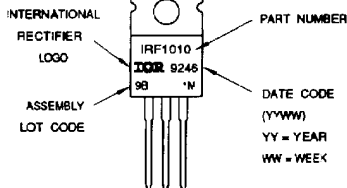
1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M, 1982
2. CONTROLLING DIMENSION: INCH.
3. OUTLINE CONFORMS TO JEDEC OUTLINE TO-220-AB.
4. HEAT SINK & LEAD MEASUREMENTS DO NOT INCLUDE BURRS.

Part Marking Information

Appendix C

TO-220AB

EXAMPLE: THIS IS AN IRF1010 WITH
ASSEMBLY LOT CODE 9B1M



Printed on Signal recycled offset,
made from 50% recycled waste paper, including
10% de-inked, post-consumer waste.



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IRI Rectifier

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